NEWS RELEASE

Hitachi High-Tech HITACHI

Hitachi High-Technologies Corporation
24-14,Nishi-shimbashi 1-chome,Minato-ku,Tokyo 105-8717,JAPAN

December 6, 2011

Hitachi High-Tech Launches Sale of a New High-speed Die Bonder for Miniature Microchips
-Semiconductor Manufacturing Equipment From Hitachi High-Tech Instruments Co., Ltd.-

Hitachi High-Technologies Corporation (TOKYO: 8036, Hitachi High-Tech) announced today the launch of the DB-900, a new high-speed die bonder from its wholly-owned subsidiary Hitachi High-Tech Instruments Co., Ltd. Hitachi High-Tech will now work to expand sales of the new product.

Die bonders are equipment used in the die bonding process of manufacturing semiconductors. This equipment performs the function of removing semiconductor chips diced from semiconductor wafers and mounting them onto various interposers, including lead-frames and microchip substrates.

Semiconductors have rapidly miniaturized and been mounted in growing numbers with the accelerated downsizing and growing functional sophistication of mobile devices. Meanwhile, the enlargement of semiconductor wafers has progressed from 6 or 8 inches in diameter, to 12 inches. Such developments have placed higher demands in productivity on the semiconductor manufacturing equipment.

Hitachi High-Tech's existing product line of die bonders, comprised of the CM-700 Series for mounting DRAM chips in packages, and the DB-700 and DB-800 for manufacturing NAND flash memory chips, has won market acclaim for high productivity and reliability. Based on the highly reliable operation control technology and 12-inch-wafer compatibility this product line has achieved in the memory chip market, the DB-900 is equipped with a newly-designed high-speed bond head for the middle-end chip assembly market. The new die bonder is designed to accommodate a 0.15mm pitch for miniature microchips and achieves a throughput of 18,000 UPH(*) via a high-speed linear motor and paste application system.

The major market for assembly of analog devices, commodity microprocessors and telecommunications devices of the DB-900 is centered in China and Southeast Asia. As such, Hitachi High-Tech will concentrate on strengthening marketing and expanding sales of the DB-900 in this region.

We are scheduled to exhibit the DB-900 at the SEMICON Japan 2011 industrial fair held at the Makuhari Messe international exhibit and convention hall from December 7 through 9, 2011.

As a global top company in the die bonder market for memory chip, Hitachi High-Tech will endeavor to increase its market share of semiconductor manufacturing equipment even further. To this end, we will actively enter and participate in the rapidly expanding market centered on quad flat non-lead (QFN) packages and other packages for miniature commodity logic chips, and respond to all manner of needs arising in the packaging of semiconductors by enhancing our die bonder product line.

The DB-900 high-speed die bonder from Hitachi High-Tech Instruments Co., Ltd.

*18,000 UPH (Units Per Hour): 200% improvement (ver. conventional product)

Inquiry: Furitsu Oda
SMT & Assembly Systems Dept.3, SMT & Assembly Systems Div., Electronic Device Systems Business Group
Tel: +81-3-3504-7730

Media Inquiry: Aiko Matsumoto
Corporate Communications Dept., CSR Div. Tel: +81-3-3504-3258